



SOT2104-2

HVQFN124, thermal enhanced very thin quad flat package, no leads, 124 terminals, 0.55 mm pitch, 11 mm x 11 mm x 0.85 mm body

3 March 2022

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN124
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	08-03-2021
Manufacturer package code	98ASA01826D

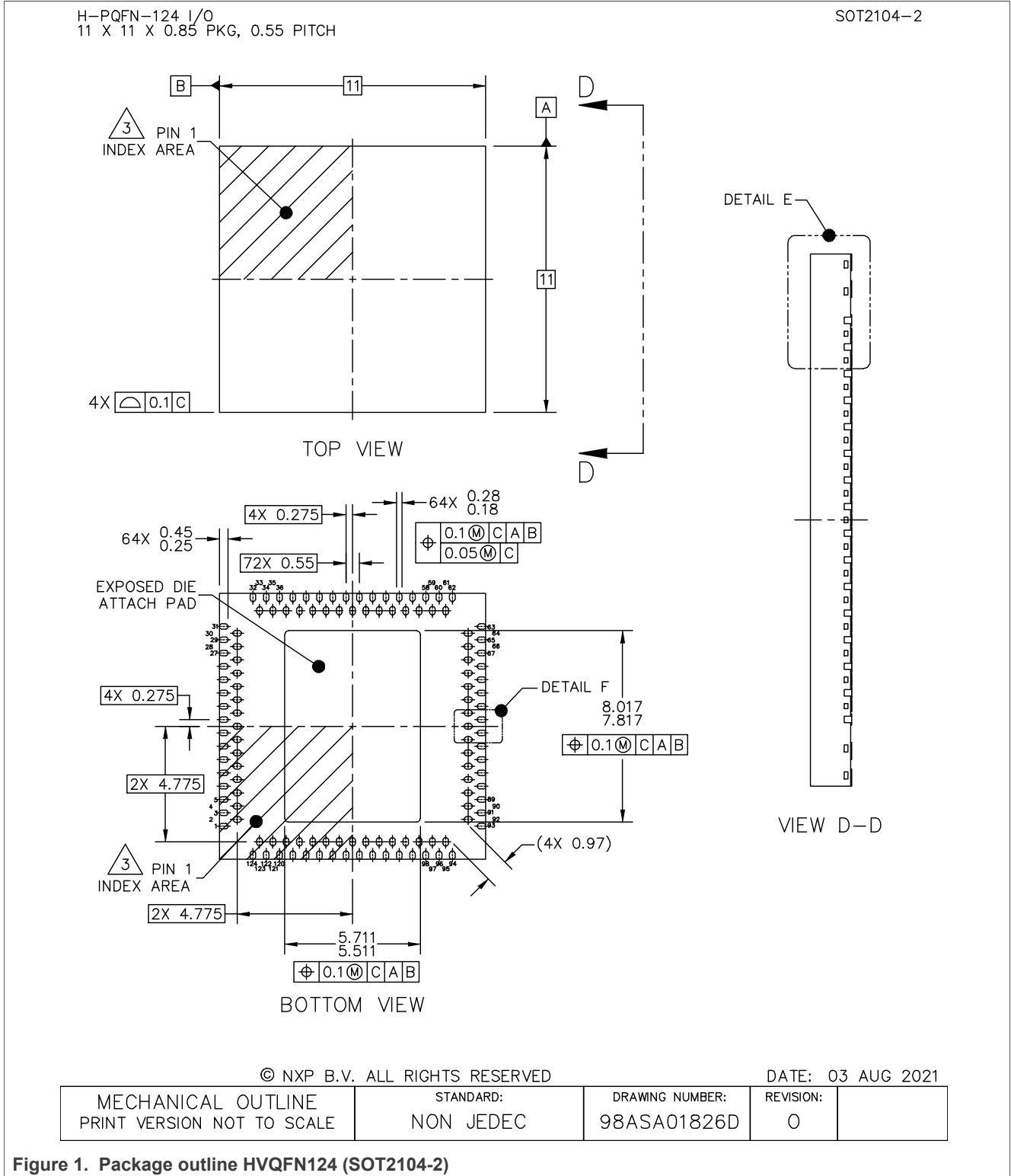
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	11	-	mm
package width	-	11	-	mm
seated height	0.8	0.85	0.9	mm
nominal pitch	-	0.55	-	mm
actual quantity of termination	-	124	-	

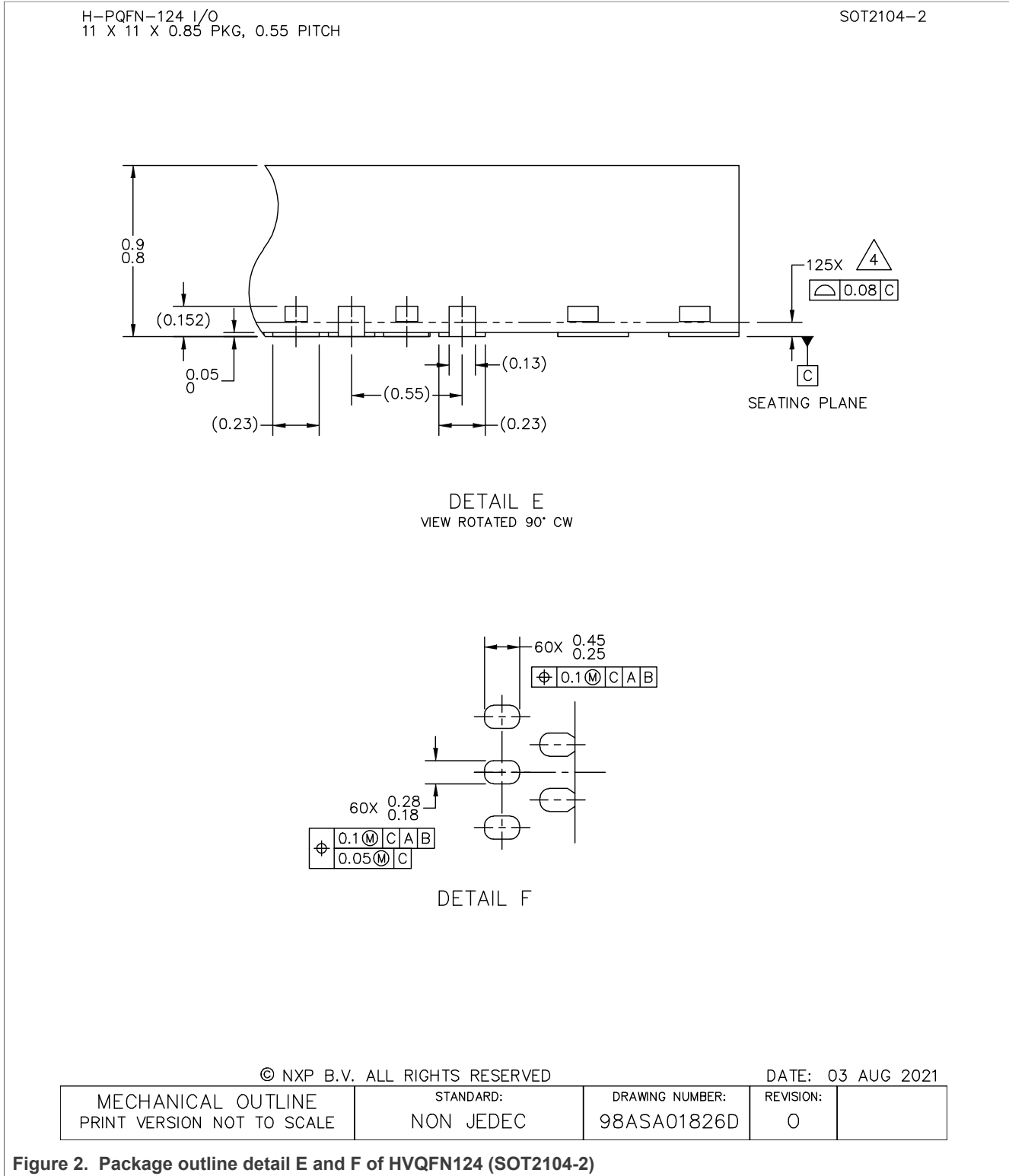


HVQFN124, thermal enhanced very thin quad flat package, no leads, 124 terminals, 0.55 mm pitch, 11 mm x 11 mm x 0.85 mm body

2 Package outline

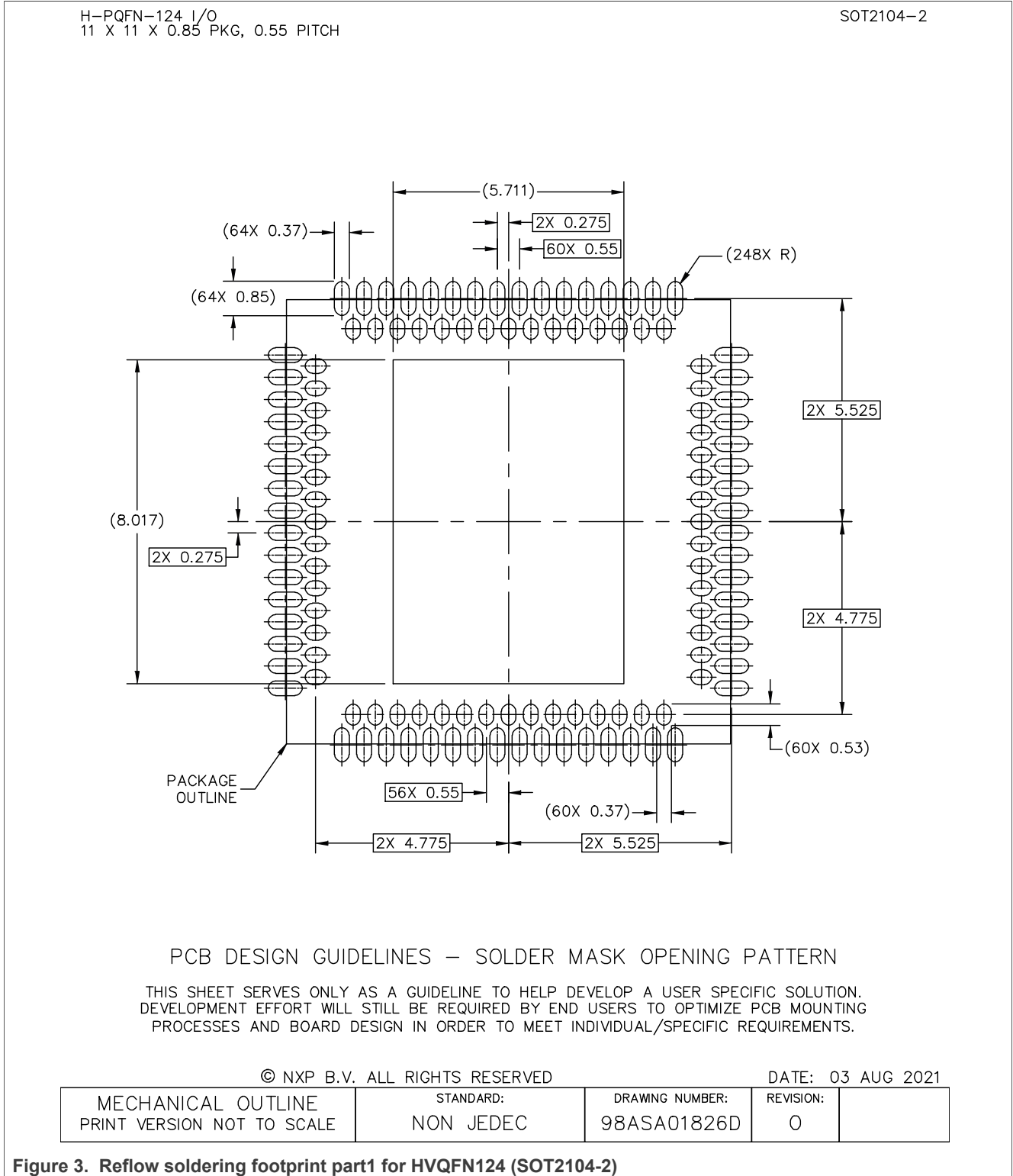


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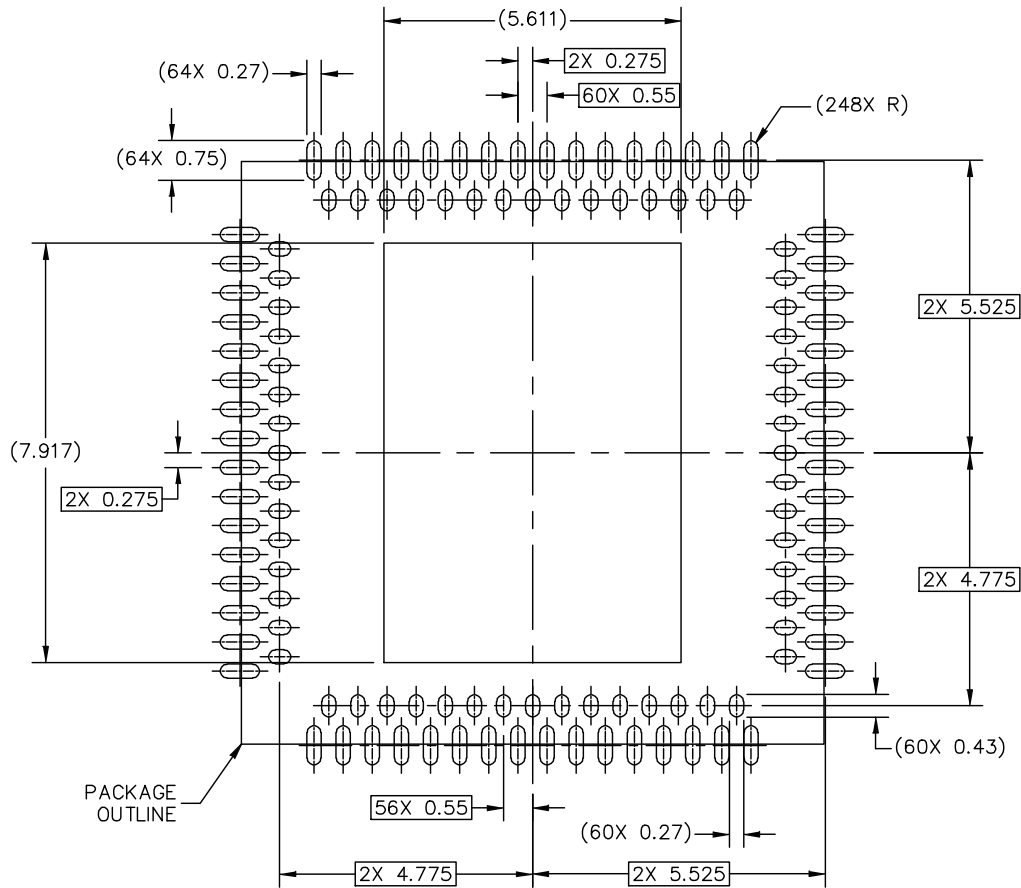
3 Soldering



HVQFN124, thermal enhanced very thin quad flat package, no leads, 124 terminals, 0.55 mm pitch, 11 mm x 11 mm x 0.85 mm body

H-PQFN-124 I/O
11 X 11 X 0.85 PKG, 0.55 PITCH

SOT2104-2



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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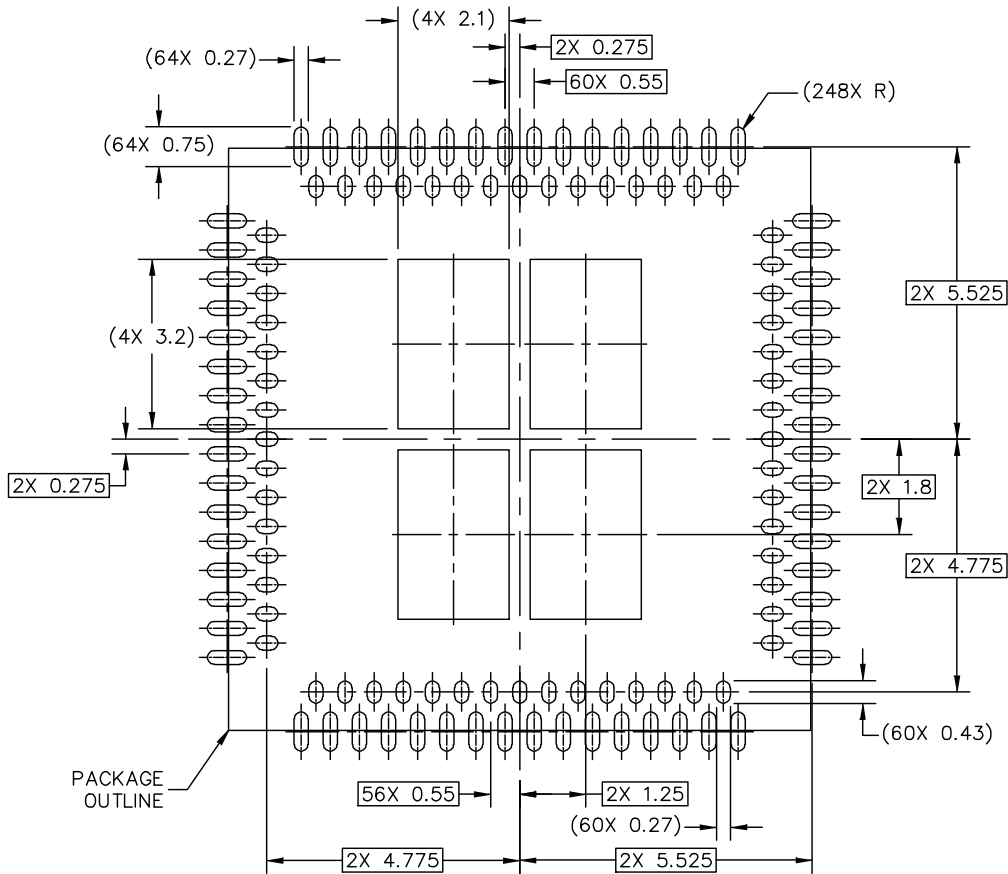
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01826D	REVISION: 0	
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Figure 4. Reflow soldering footprint part2 for HVQFN124 (SOT2104-2)

HVQFN124, thermal enhanced very thin quad flat package, no leads, 124 terminals, 0.55 mm pitch, 11 mm x 11 mm x 0.85 mm body

H-PQFN-124 I/O
11 X 11 X 0.85 PKG, 0.55 PITCH

SOT2104-2



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HVQFN124 (SOT2104-2)

HVQFN124, thermal enhanced very thin quad flat package, no leads, 124 terminals, 0.55 mm pitch, 11 mm x 11 mm x 0.85 mm body

H-PQFN-124 I/O
11 X 11 X 0.85 PKG, 0.55 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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Figure 6. Package outline note HVQFN124 (SOT2104-2)

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4 Legal information

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